
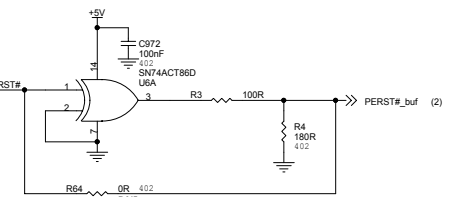
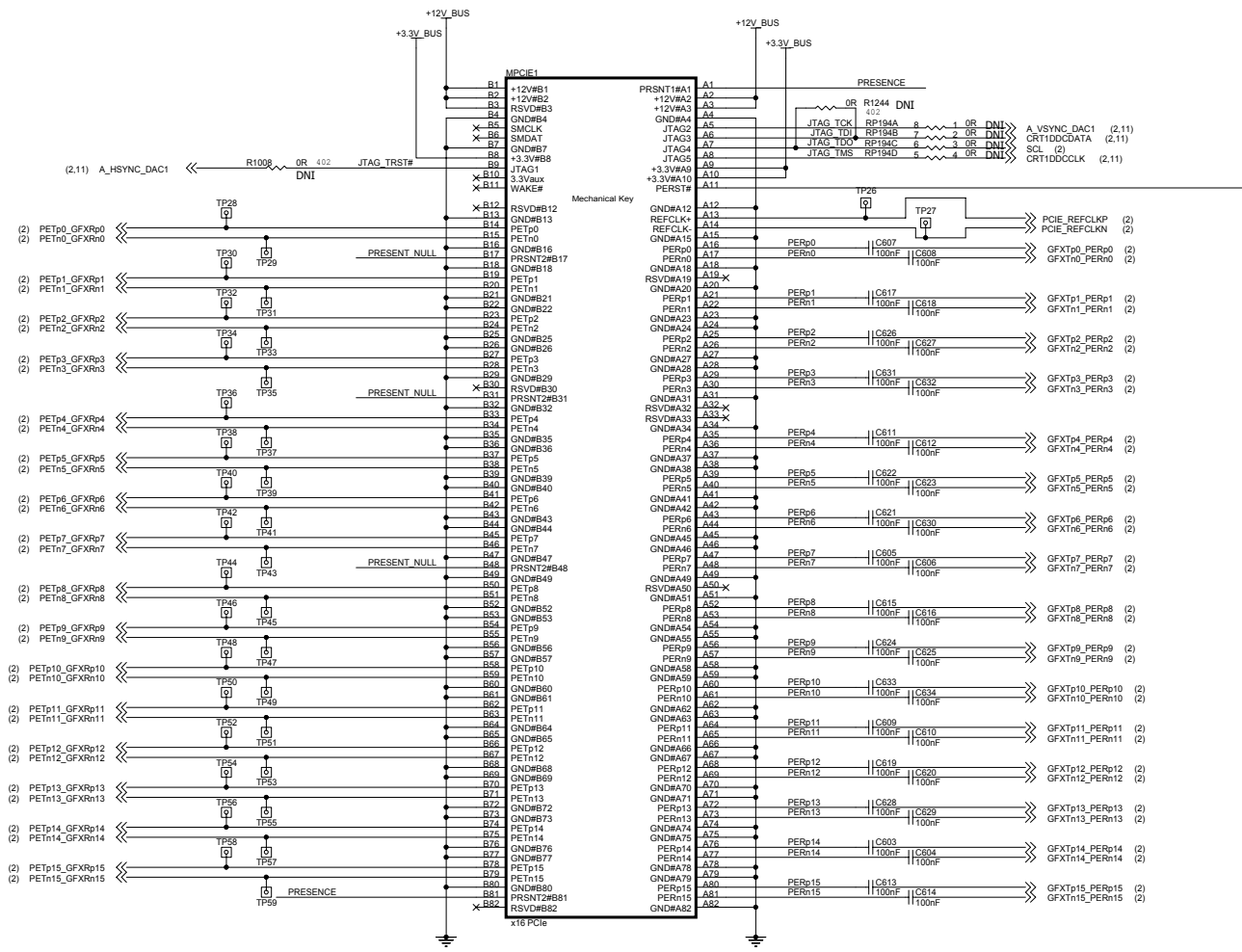




Variant Name>		5	4	3	2	1
		Title PCI-E RV370 128M TSOP VO-SV/DI			Schematic No. 105-A260xx-00	Date: Friday, April 30, 2004
REVISION HISTORY						Rev 5
Sch Rev	Date	REVISION DESCRIPTION				
0 00A	2003-09-10	<p>PRELIMINARY BASED ON 105-A181xx-00A and 105-A200xx-00</p> <ul style="list-style-type: none">- Use 402 R and C footprints as preferred- (pg1) Add 0R bypass for PERST#, and use XOR spared gate for buffer- (pg1) Keep only 1 100uF decoupling for +12V_BUS- (pg1) Connect B3 of edge connector directly to +12V_BUS- (pg2) Remove oscillator and change crystal to surface mount- (pg2) Hard pull-down on TEST_Y/MCLK- (pg2) Remove thermal interrupt, no provision for speed controlled fan- (pg2) Remove redundant TPs- (pg2) Pull-up on DVPCNTL_[3:0], remove RageTheater capture ports (VID/DVO[7:0])- (pg2) DVOMode pull-up to 1.8V, set to 12-bit DVO (1.8V DVO I/O signalling)- (pg3) Memory interface based on A198, remove Channel B- (pg4) Remove power-up diodes- (pg5, 6, 7) Redesigned power regulators- (pg8, 9) Channel A only Series-Terminated TSOP interface (based on A200)- (pg11, 12, 13) Front-end based on Low-Profile VGA/DVI + VO design (based on A200)				
	2003-09-22	<ul style="list-style-type: none">- (pg5) Add RC snubber circuit on switching regulator- (pg7) Add R124 for power dissipation				
	2003-10-16	<ul style="list-style-type: none">- (pg14) Add MT2, second mounting hole- (pg6 and 7) Remove R817, option for sharing REG8 and REG9, due to layout concerns- (pg4) Add C979..C985 On request of EMI team. These are for decoupling adjacent planes.- (pg6) Make RP2 dual footprint with 0402 Caps C986..C989. Created a similar circuit using RP195 and C990..C993. The RP can be used to short +MVDDQ and +MVDDC, and the caps can be used to decouple the planes.- (pg6) Add C973..C978 Decoupling caps. These are placed accross +MVDDQ/+MVDDC plane splits- (pg11) Remove R994..R996 stitching GND to Chassis GND.				
1 00B	2003/11/14	<ul style="list-style-type: none">- (Layout) Change to 6-layer PCB- (Layout) Change PCIE test points- (pg1) Change PCIE test points, add 3.3V_BUS polymer cap, add R1244- (pg2) Add R23 for DVO pull-down- (pg4) Add B15 for +3.3V_BUS VDDR4 alternate, change PCIE regulators filter from 100nF to 1uF- (pg5) Add stand-alone +PCIE_VDDR, +PCIE_PVDD12 and +PCIE_PVDD18 regulators, improve power sequence circuit- (pg5) Add R315 and R316 to Select +12V_BUS or +5V for boot circuit, change R368 footprint to 603- (pg6) Add C314 and C315 for MVDDC and MVDDQ, 1.8V from PCIE_PVDD18- (pg7) Remove R124, add polymer cap for PCIE_PVDD18, add +PCIE_VDDR and +PCIE_PVDD12 tied option and single package FET for +PCIE_VDDR- (pg14) Add fan connector				
2 00C	2004/03/05	<ul style="list-style-type: none">- (pg02, 10) Fix pull-up +VDD_DVO to +VDDR4- (Layout) TVO filters move close to connector- (pg04) Remove CP2, 3, 4, 5, 6 and 8 for dual footprint manufacturing issues (Capacitor packs sharing with 402 footprints)- (Layout) Components using the same foot print. (remove MC2)- (pg06) Remove C986, C987, C988, C989, C990, C991, C992 and C993- (pg06) Add C800 for options- (pg11) +5V supply with current limiting for VESA DDC spec, remove F1, B21- (pg05) Remove dual-packaged MOSFET- (Layout/EMI) C507, C508, C509, R513, R514, R515 (added), L60, L61 and L62 connect to digital Gnd instead of chassis Gnd.				
3 00E 00D and 00E are in parallel	2004/04/16	<ul style="list-style-type: none">- (pg04) Remove redudant dual-footprint capacitor array- (pg11) Add R994, extra resistor to tide chassis/digital ground- (pg12) Add R916 and R917 for +5V_VESA resistor dissipation to meet 70% derating spec- (pg13) Remove R513 and R514 and tide TVO MiniDIN shield directly to chassis ground				
4 00D 00D and 00E are in parallel	2004/04/16	<ul style="list-style-type: none">- (pg11, 12, 13 and 14) Change chassis ground to digital ground- (pg11) Remove R991, R992, R993, R994, R997, R998 and R999 for chassis/digital ground tide- (pg12) Change DVI-I connector to fully-shielded connector- (pg14) Remove Mounting Hole MT2- (Layout) Remove TMDS ground guards				
5 00	2004/04/27	<p>Released based on -00D PCB (not -00E)</p> <ul style="list-style-type: none">- (pg05) Tide R357 to +3.3V instead of +12V for proper power sequence				
		5	4	3	2	1

USE 47uF TANTALUM CAPACITOR OR HIGHER

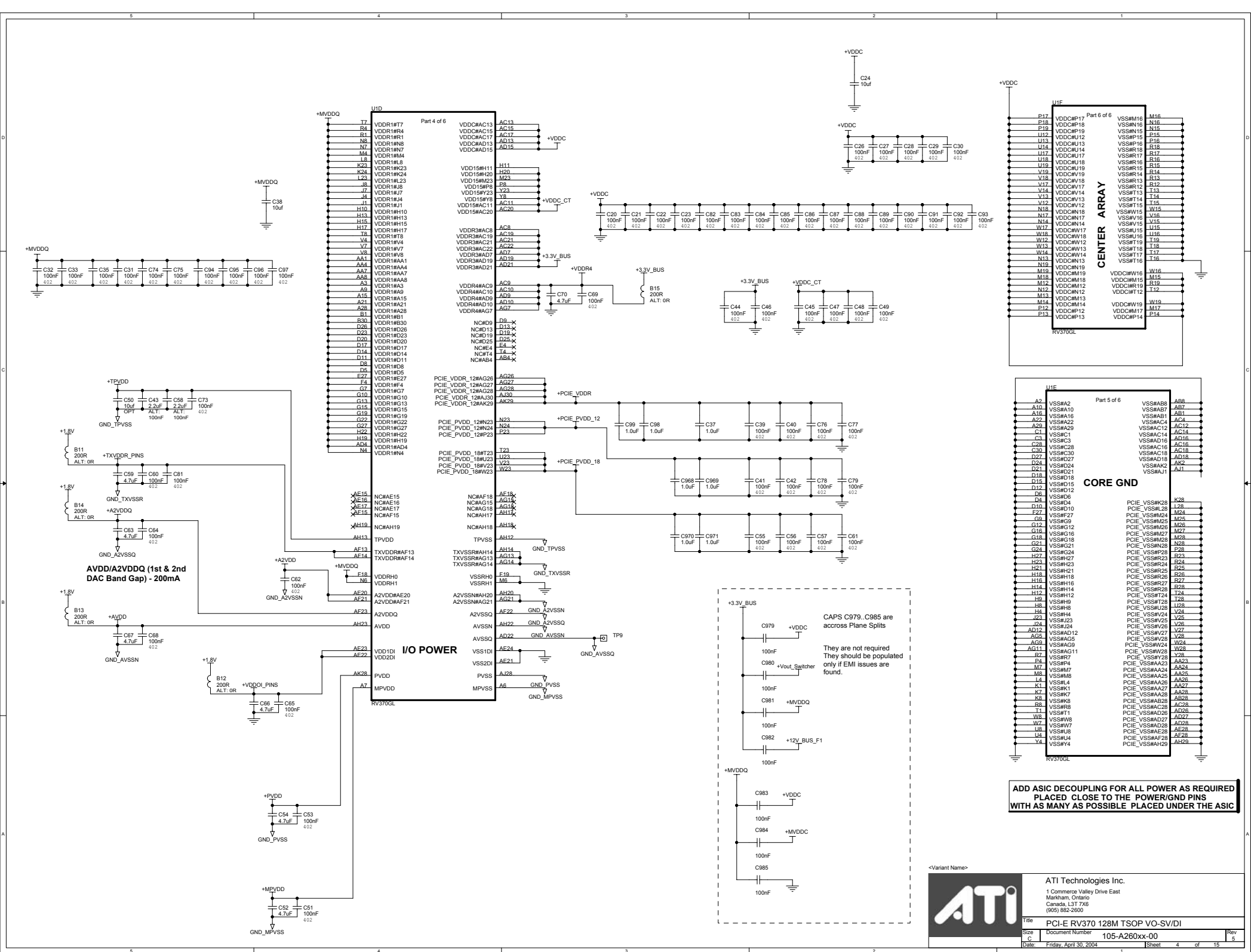


SYMBOL LEGEND	
DNI	DO NOT INSTALL
#	ACTIVE LOW
	DIGITAL GROUND
	ANALOG GROUND



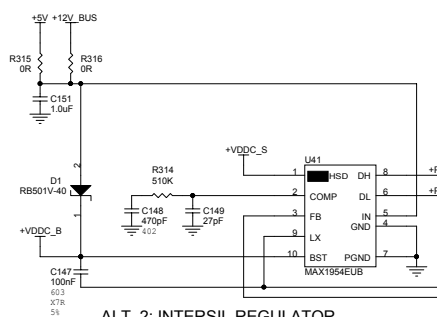
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(905) 882-2600

Title		PCI-E RV370 128M TSOP VO-SV/DI	
Size	Document Number	105-A260xx-00	Rev
C			5
Date:	Friday, April 30, 2004	Sheet	1 of 15

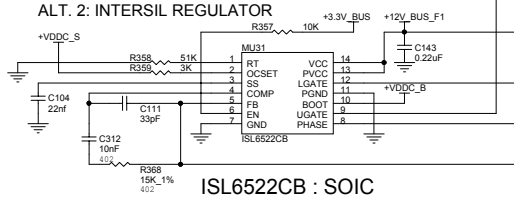


Vout = 1.2V ~ 1.3V

ALT. 1: MAXIM REGULATOR

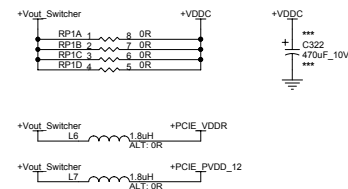
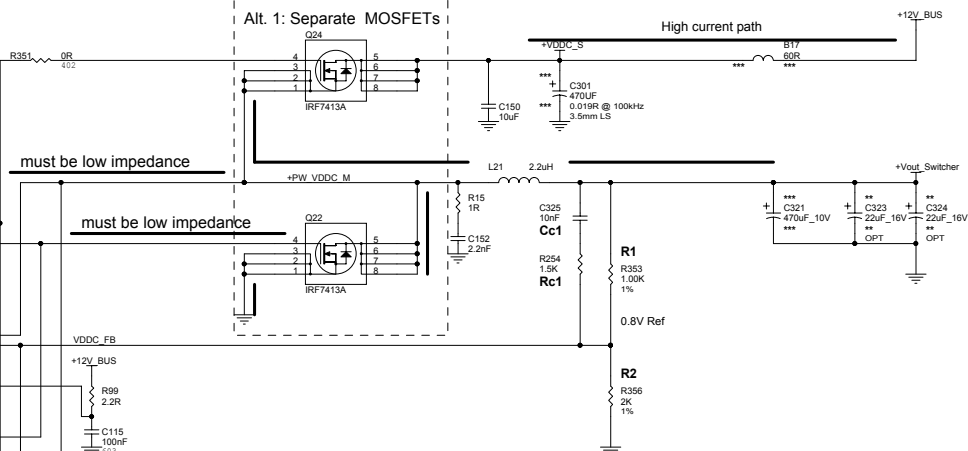


ALT. 2: INTERSIL REGULATOR

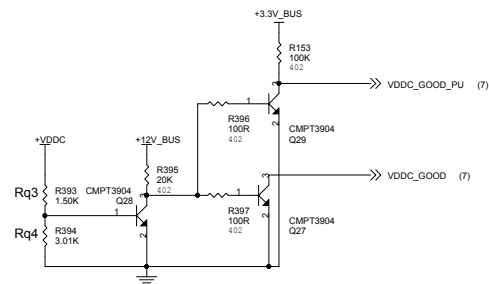


ISL6522CB : SOIC

Alt. 1: Separate MOSFETs



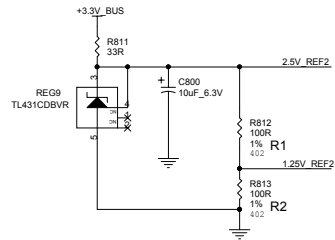
+VDDC	Rq3	Rq4
+1.3V	1.5K	2.4K
+1.2V	1.5K	3K



*** Indicate number of power via required for the connection

Part	NOTES
MAX1954	Do not install Cc1, Rc1
ISL6522	Install Cc1, Rc1

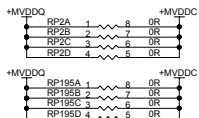
Part	Vout	R1	R2
MAX1954 ISL6522	1.2V	1.00K 1% ATI P/N 3240100100	2.00K 1% ATI P/N 3240200100
0.8V Ref	1.3V	1.00K 1% ATI P/N 3240100100	1.6K 1% ATI P/N 3240162100



Voltage Req.	R1	R2
0.8V	150R P/N 3160150000 402	71.5R P/N 324075R500
1.25V	100R P/N 3160100000 402	100R P/N 3160100000 402
1.5V	100R P/N 3160100000 402	150R P/N 3160150000 402
1.8V	54.9R P/N 3240054900	140R P/N 3240140000
1.84V	49.9R P/N 3240049900	140R P/N 3240140000

Voltage Req.	Rx1 for 1.25V Ref	Rx2 for 1.25V Ref
1.5	432R P/N 3240432000	2.15K P/N 3240215100
1.6V	432R P/N 3240432000	1.5K P/N 3240150100
1.7V	432R P/N 3240432000	1.21K P/N 3240121100
1.8175V	681R P/N 3240681000 603 P/N 3160681000 402	1.5K P/N 3240015200

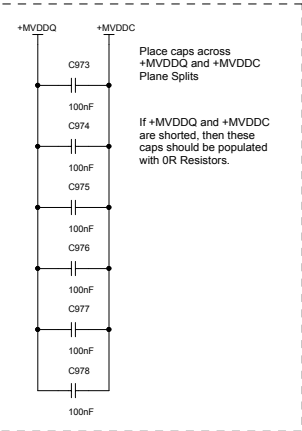
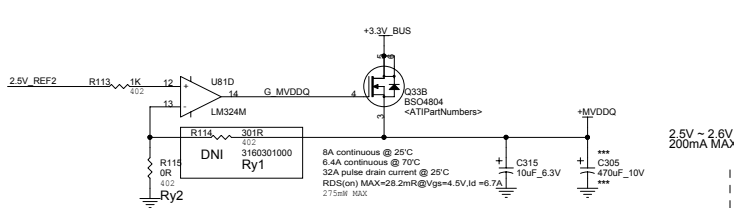
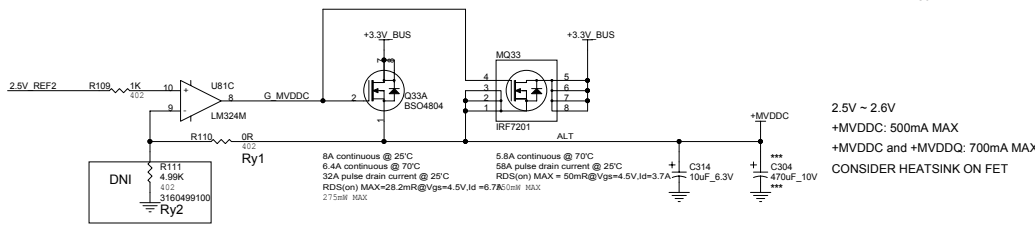
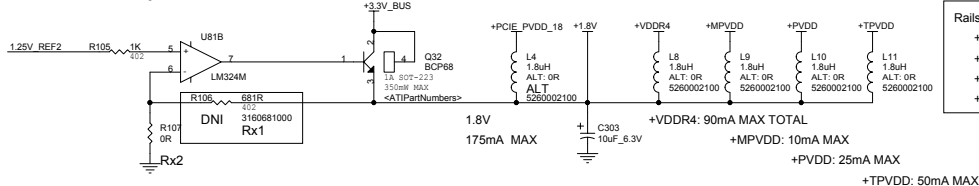
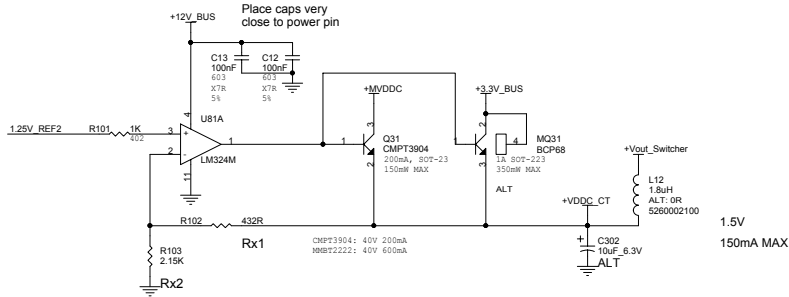
Voltage Req.	Ry1 for 2.5V Ref	Ry2 for 2.5V Ref
3.3V	1.07K P/N 3240107100	3.32K P/N 3240332100
2.7V	301R (402, 1%) P/N 3160301000	3.32K P/N 3240332100
2.65V	301R (402, 1%) P/N 3160301000	4.99K (402, 1%) P/N 3160499100
2.61V	221R (402, 1%) P/N 3160221000	4.99K (402, 1%) P/N 3160499100
2.5V	OR P/N 3230000000 603 P/N 3150000000 402	DNI



Alt. regulator for +PVDD
Vout = 1.8V
Iout = 30mA MAX

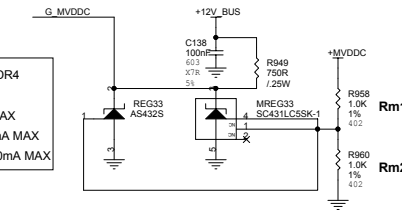
Alt. regulator for +MPVDD
Vout = 1.8V
Iout = 10mA MAX

Alt. regulator for +TPVDD
Vout = 1.65V ~ 1.85V
Iout = 20mA MAX



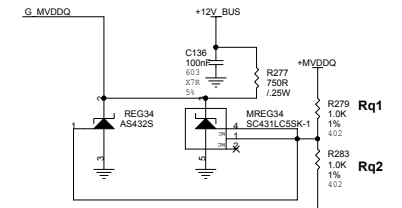
Alt. regulator for +MVDDC
Vout = 2.5V ~ 2.6V
Iout = 500mA MAX

Voltage Req.	Rm1	Rm2
3.34V [-0.04V/+0.04V]	4.32K	2.55K
3.45V [-0.04V/+0.04V]	4.32K	2.43K
2.5V [-0.03V/+0.03V]	1K 3240100100	1K 3240100100

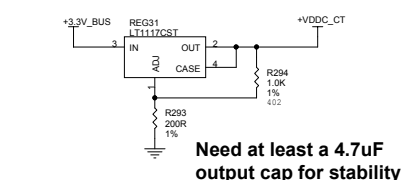


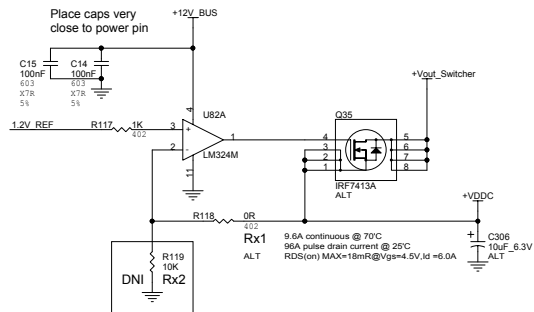
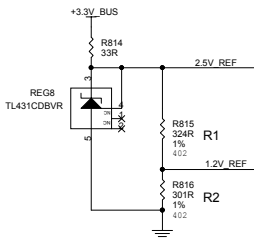
Alt regulator for +MVDDQ
Vout = 2.5V ~ 2.6V
Iout = 200mA MAX

Voltage Req.	Rq1	Rq2
1.8V [-0.09V/+0.18V]	681R 3240681000	1.5K 3230015200
2.5V	1K 3240100100	1K 3240100100
2.6V	4.75K 3240475100	4.32K 3240432100

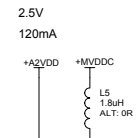


Alt regulator for +VDDC_CT
Vout = 1.5V
Iout = 150mA MAX

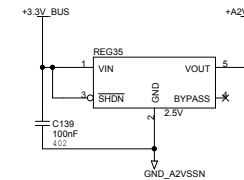




1.3V
8A MAX
MIGHT NEED HEATSINK ON FET

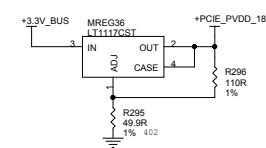


Alt. regulator for +A2VDD
Vout = 2.5V
Iout = 120mA MAX



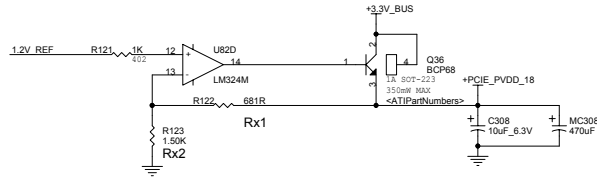
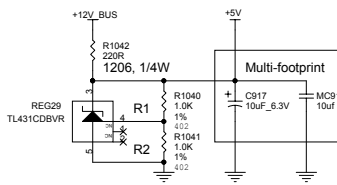
+A2VDD and GND_A2VSSN routed with at least 15 mil trace and not longer than 1.5 inch.

Alt. regulator for PCIE_PVDD_18
Vout = 1.82V
Iout = 500mA MAX



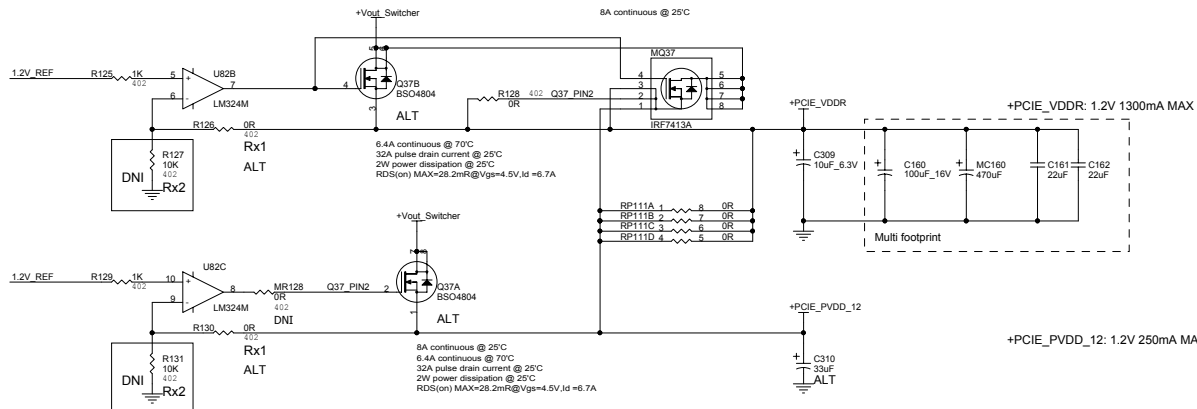
Need at least a 10uF Tant. output cap for stability
Min. Load Current: 10mA

Regulator for +5V
Vout = 5V
Iout = 20mA MAX

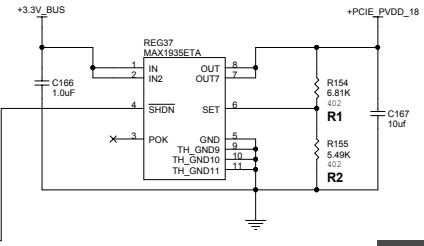
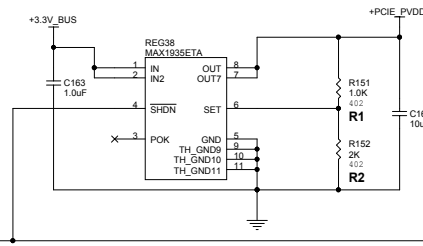
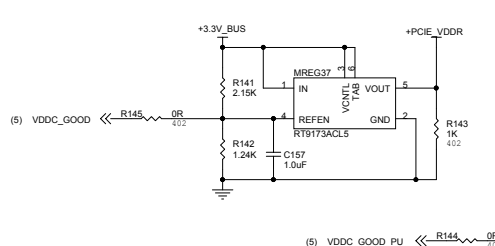


+PCIE_PVDD_18: 1.8V 500mA MAX

Optional when +Vout_Switcher is above 1.2V



+PCIE_PVDD_12: 1.2V 250mA MAX

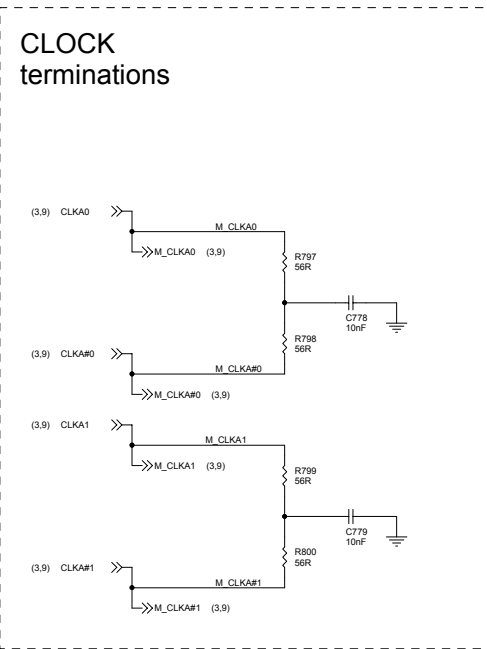
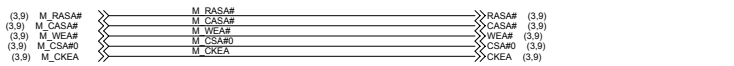
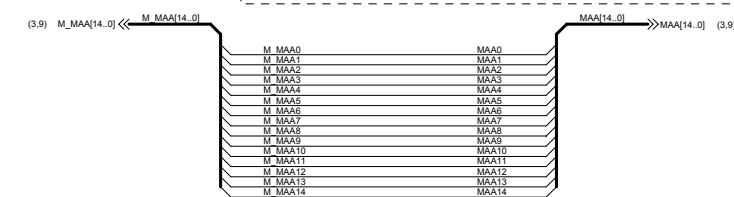
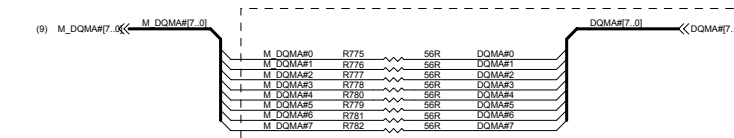
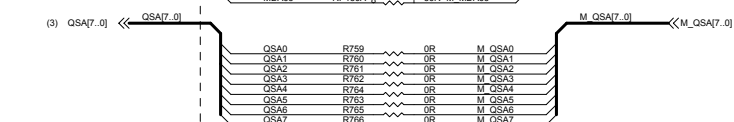
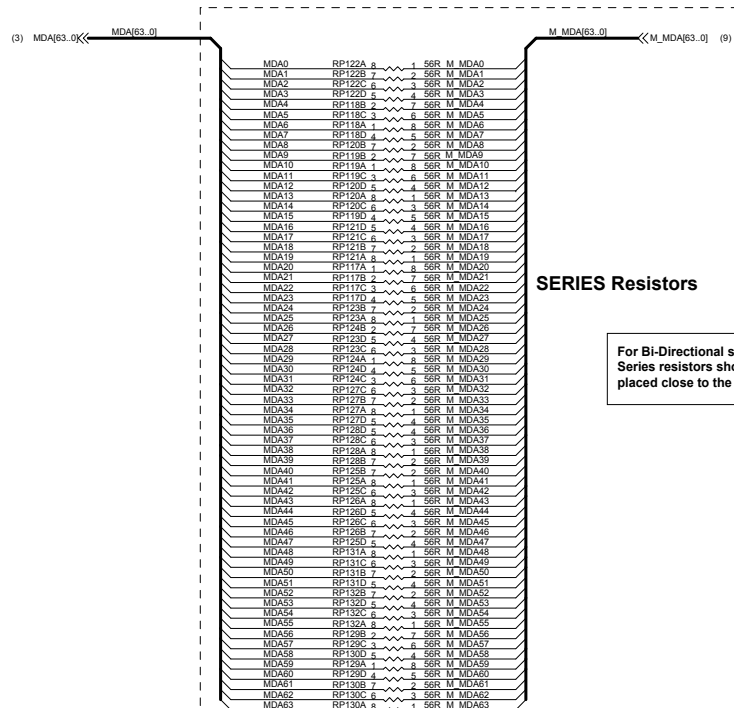


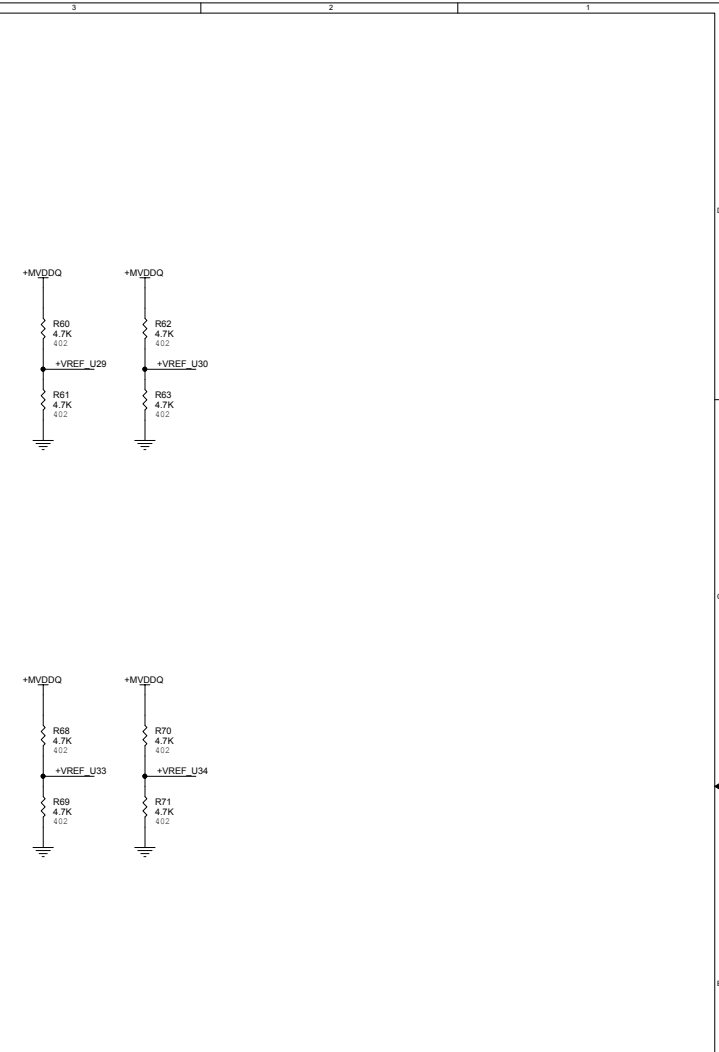
Part	Vout	R1	R2
MAX1935 0.8V Ref	1.2V	1.00K 1% 412 ATI P/N 3160100100	2.00K 1% 402 ATI P/N 3160200100
	1.79V	6.81K 1% ATI P/N 3160681100	5.49K 1% 402 ATI P/N 3160549100



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Title: PCIe RV370 128M TSOP VO-SV/DI
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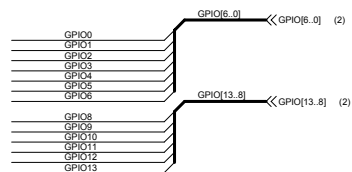
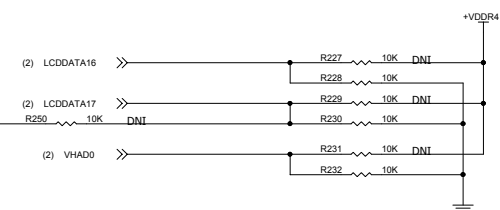


Title	PCI-E RV370 128M TSOP VO-SV/DI
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Size	Document Number	105-A260xx-00	Rev	5
Custom	Date:	Friday, April 30, 2004	Sheet	9 of 15

The diagram illustrates the +3.3V_BUS connections for the Raspberry Pi 4 Model B. The bus is connected to various GPIO pins through pull-up resistors (R201-R238). The pins are labeled with their function: GPIO0 (DESKTOP), GPIO1 (DESKTOP), GPIO2 (DNT), GPIO3 (Turmwat), GPIO4 (DNT), GPIO5 (DNT), GPIO6 (DNT), GPIO11 (DNT), GPIO12 (DNT), GPIO13 (DNT), GPIO9 (DNT), GPIO8 (DNT), (2) Mem_Strap0 (DNT), and (2) Mem_Strap1 (DNT).

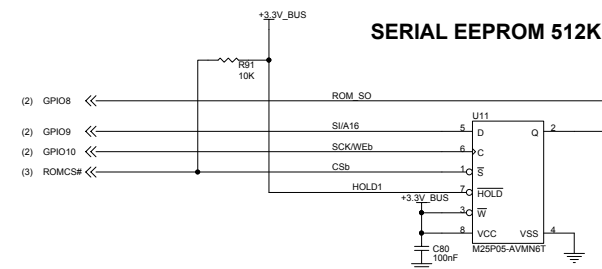
GPIO Pin	Resistor	Value	Function
GPIO0	R201	10K	DESKTOP
	R202	10K	MOBO
GPIO1	R203	10K	DESKTOP
	R204	10K	MOBO
GPIO2	R205	10K	DNT
	R206	10K	
GPIO3	R207	10K	Turmwat
	R208	10K	Grantsdale
GPIO4	R219	10K	
	R220	10K	DNT
GPIO5	R221	10K	DNT
	R222	10K	
GPIO6	R223	10K	DNT
	R224	10K	
GPIO11	R209	10K	DNT
	R210	10K	
GPIO12	R211	10K	DNT
	R212	10K	
GPIO13	R213	10K	
	R214	10K	DNT
GPIO9	R215	10K	
	R216	10K	DNT
GPIO8	R217	10K	DNT
	R218	10K	
(2) Mem_Strap0	R235	10K	DNT
	R236	10K	
(2) Mem_Strap1	R237	10K	DNT
	R238	10K	



STRAPS	PIN	DESCRIPTION	ASIC DEFAULT
STRAP_B_PTX_PWRS_ENB	GPIO0	Transmitter Power Savings Enable 0: 50% Tx output swing for mobile mode 1: full Tx output swing	0
STRAP_B_PTX_DEEMPH_EN	GPIO1	Transmitter De-emphasis Enable 0: Tx de-emphasis disabled for mobile mode 1: Tx de-emphasis enabled	0
PCIE_MODE(1:0)	GPIO(3:2)	00: PCI Express 1.0A mode (Grantsdale) 01: Kyrene-compatible mode 10: PCI Express 1.0 mode (Turmwater) 11: PCI Express 1.0A mode and short-circuit internal loopback mode (Rx connected directly to Tx of PHY)	00
STRAP_B_PTX_IEXT	GPIO4	Transmitter Extra Current 0: normal mode 1: extra current in Tx output stage - potential power savings for mobile mode	0
STRAP_FORCE_COMPLIANCE	GPIO5	Force chip to go to Compliance state quickly for Tester purposes 0: normal operational mode 1: compliance mode	0
STRAP_B_PPLL_BW	GPIO6	PLL Bandwidth 0: full PLL Bandwidth 1: reduced PLL bandwidth	0
STRAP_DEBUG_ACCESS	GPIO6	Strap to set the debug muxes to bring out DEBUG signals even if registers are inaccessible.	0
ROMIDCFG(3:0)	GPIO(9,13:11)	If no ROM attached, controls chip iDIs. If rom attached identifies ROM type 0000 - No ROM, CHG_ID=0 0001 - No ROM, CHG_ID=1 0100 - reserved 0110 - reserved 1000 - Parallel ROM, chip iDIs from ROM 1001 - Serial AT25F1024 ROM (Atmel), chip iDIs from ROM 1010 - Serial AT45DB011 ROM (Atmel), chip iDIs from ROM 1011 - Serial M25P10 ROM (ST), chip iDIs from ROM 1100 - Serial M25P05 ROM (ST), chip iDIs from ROM 1101 - Serial NX25F011B ROM (ISSI), chip iDIs from ROM	
VIP_DEVICE	DVPDATA_20 (VHADO net)	Indicates if any slave VIP host devices drove this in low during reset. 0 - Slave VIP host port devices present 1 - No slave VIP host port devices reporting presence during reset	

STRAP P	INTERRUPT
LOW	ENABLED (DEFAULT)
HIGH	DISABLED

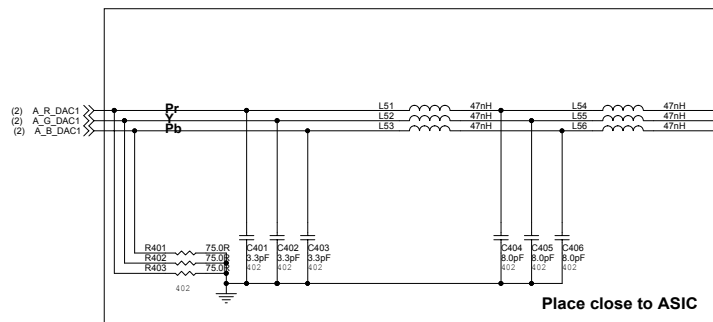
MEMORY TYPE STRAPS		
	Mem_Strap0	Mem_Strap1
SAM	0	0
INF	1	0
HYN	0	1
ELPIDA	1	1



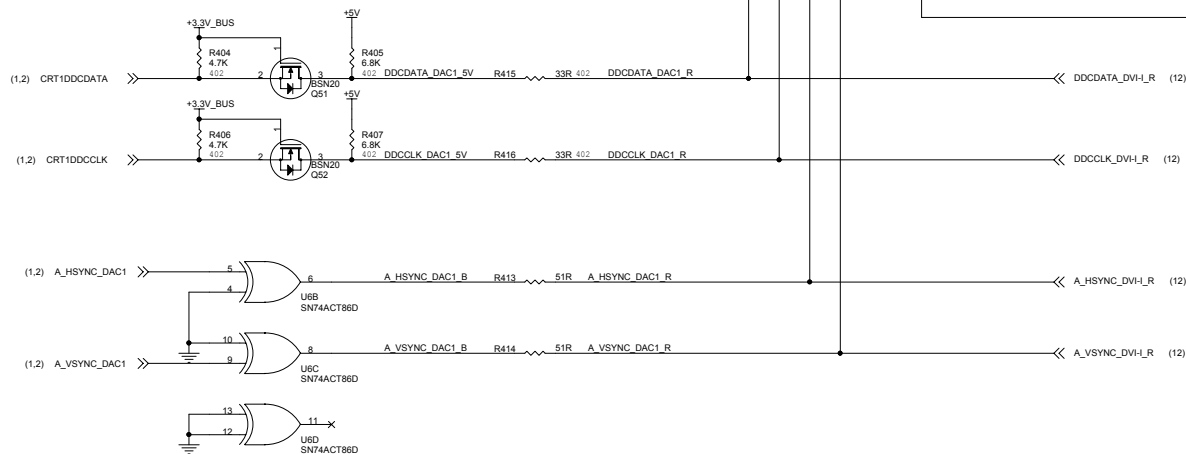
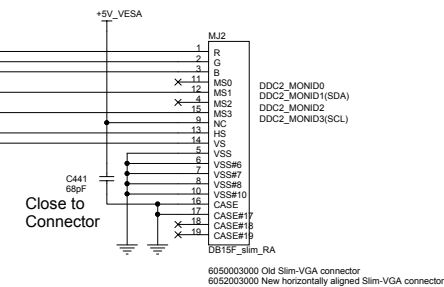
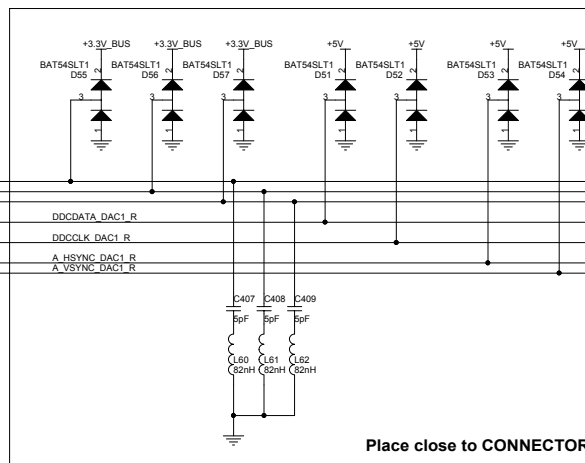
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PRIMARY CRT

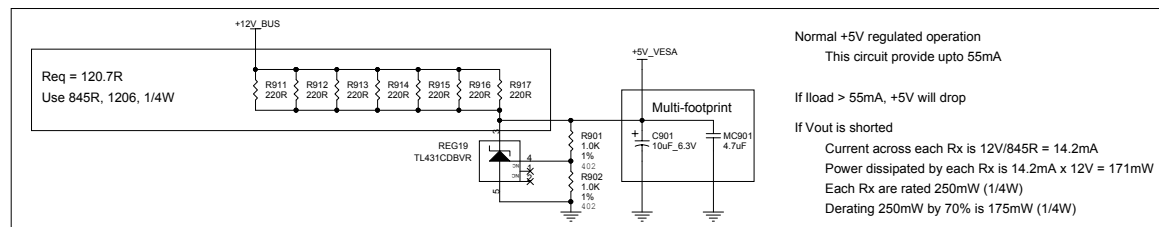
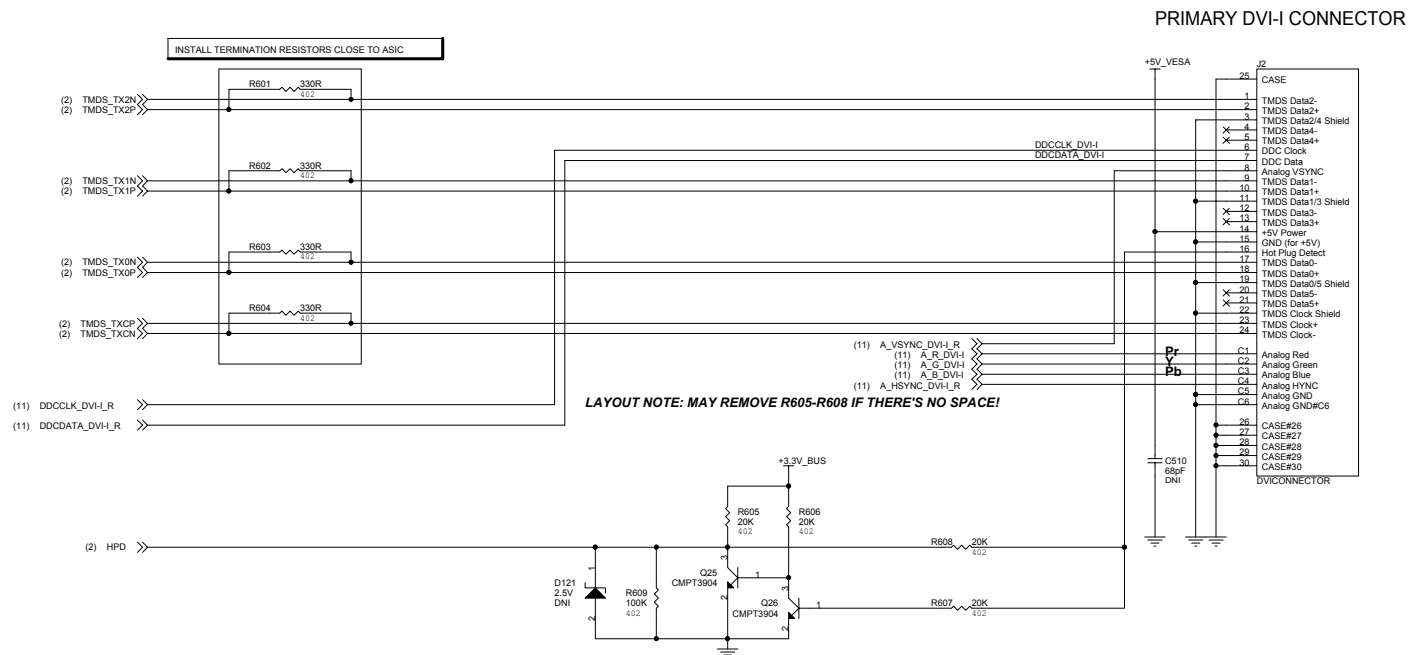


OPTIONAL ESD/HOTPLUG PROTECTION DIODES



DB15 pin	Standard VGA	DDC1 Host	DDC2B or DDC2B+ Host	DDC2AB Host	DDC1/2 Display
11	Monitor ID bit 0	Monitor ID bit 0	Monitor ID bit 0	Monitor ID bit 0	Optional
12	Monitor ID bit 1	Monitor ID bit 1	Monitor ID bit 1	Monitor ID bit 1	Optional
4	Monitor ID bit 2	Monitor ID bit 2	Monitor ID bit 2	Monitor ID bit 2	Optional
15	Monitor ID bit 3	Open	SDA	SCL	Optional
9	N/C	+5V	+5V	+5V	Optional
Hardware Support	No	Yes	Yes	No	Yes

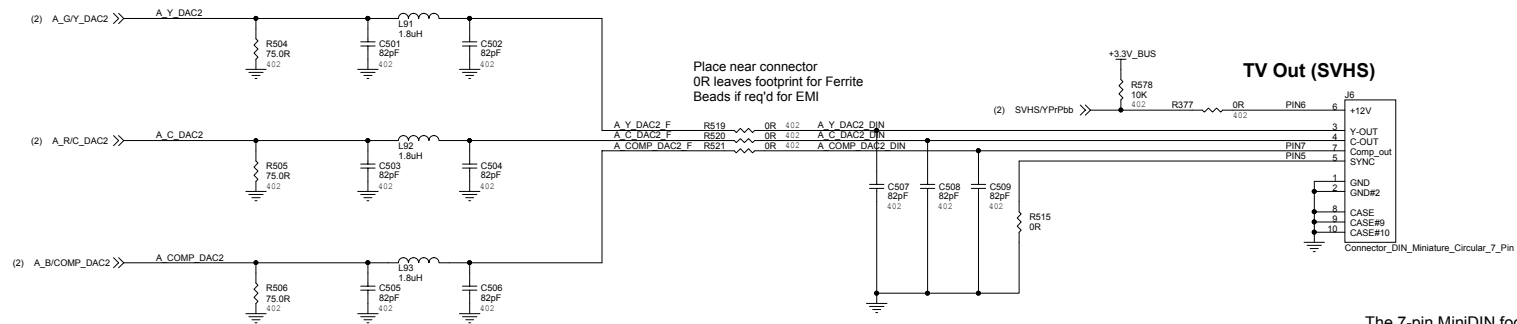
Based on VESA Display Data Channel (DDC) Standard Ver. 3 Dec. 15, 1997



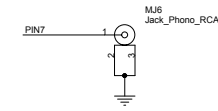
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(905) 882-2600

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Place Resistors close to ASIC.



The 7-pin MiniDIN footprint allows one of the two MiniDINs:
 - 7-pin Svideo/Composite MiniDIN P/N 6071001500
 - 4-pin Svideo MiniDIN P/N 6070001000



DVI/VGA SCREWS



Bracket Screws



MISC. BOARD PARTS



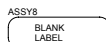
6_X_11



ATI_LOGO_LABEL



ATI_LOGO_LABEL



9050005900;9050005900;9050005900;9050005900;9050005900

ATX Brackets



NO TABS, DVI
80200321A0

DVI ATX



TOP TAB (LP), DIN, DVI
8020033000

DVI+MiniDIN ATX

DNE

Slim-VGA ATX

6052003000 New horizontally aligned Slim-VGA connector



TOP TAB (LP), DIN, VGA
6052003000 New horizontally aligned Slim-VGA connector

Slim-VGA+MiniDIN ATX

LP Brackets



LP, NO TABS, DVI
8020032600

DVI LP



LP, TOP TAB, DIN, DVI
8020032700

DVI+MiniDIN LP



LP, NO TABS, VGA
80200328A0

Slim-VGA LP

No Top Tab

6052003000 New horizontally aligned Slim-VGA connector



TOP TAB, DIN, VGA
80200327A0

Slim-VGA+MiniDIN LP

6052003000 New horizontally aligned Slim-VGA connector



HEATSINK
7120005800



HEATSINK
7120005100



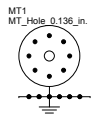
HEATSINK
7120002700



HEATSINK
7120008500

Spring push-pin

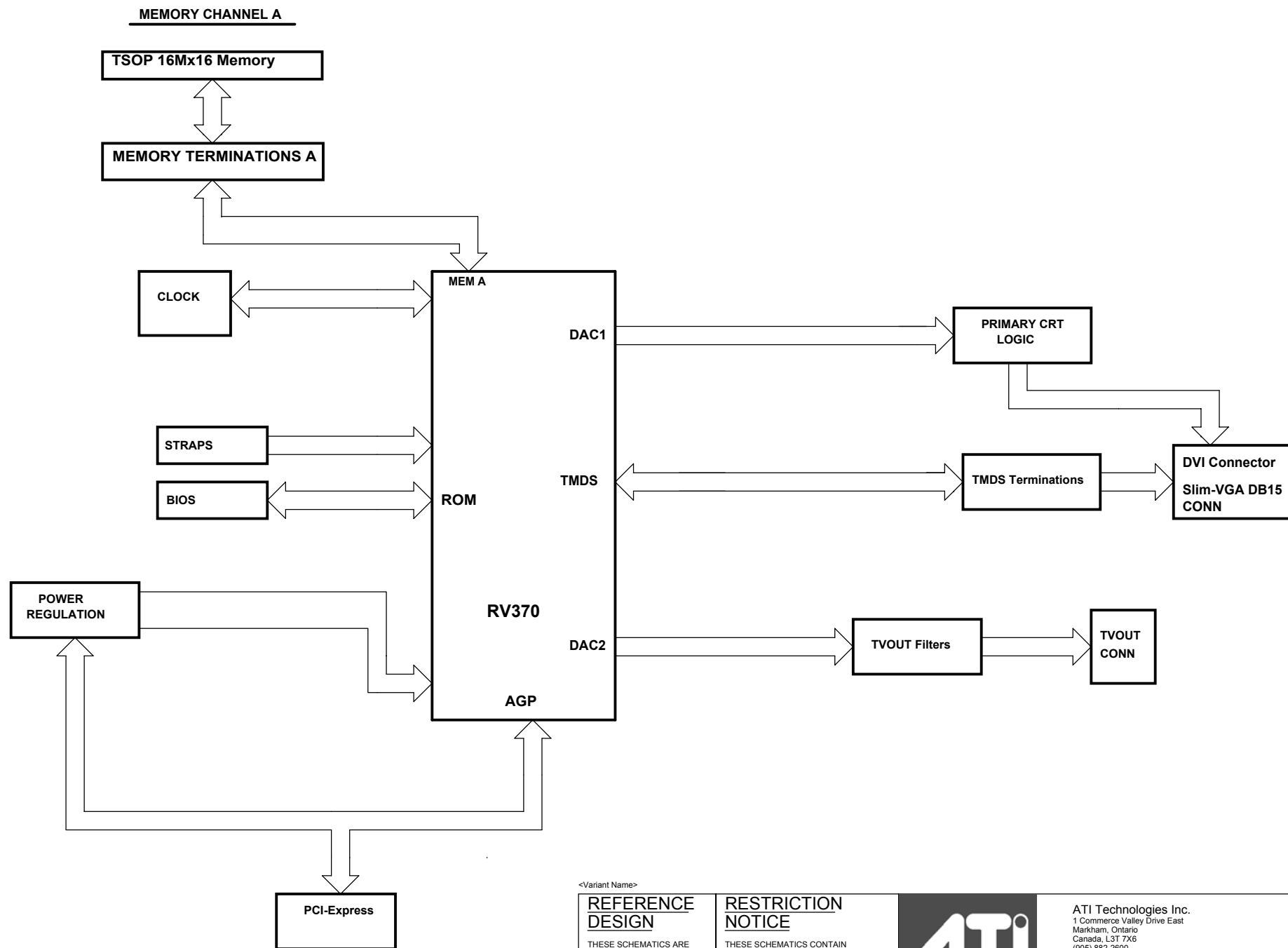
ITW push-pin



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<Variant Name>

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